Renesas Electronics America Inc - M3087BFLAGP#U3 Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, EBI/EMI, I²C, IEBus, IrDA, SIO, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	121
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 34x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m3087bflagp-u3

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

   "Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

1. Overview

1.1 Features

The M32C/87 Group (M32C/87, M32C/87A, M32C/87B) is a single-chip control MCU, fabricated using high-performance silicon gate CMOS technology, embedding the M32C/80 Series CPU core. The M32C/87 Group (M32C/87, M32C/87A, M32C/87B) is housed in 144-pin and 100-pin plastic molded LQFP/QFP packages.
With a 16-Mbyte address space, this MCU combines advanced instruction manipulation capabilities to process complex instructions by less bytes and execute instructions at higher speed.
The M32C/87 Group (M32C/87, M32C/87A, M32C/87B) has a multiplier and DMAC adequate for office automation, communication devices and industrial equipment, and other high-speed processing applications.

1.1.1 Applications

Audio components, cameras, office equipment, communication devices, mobile devices, etc.

1.1.2 Specifications

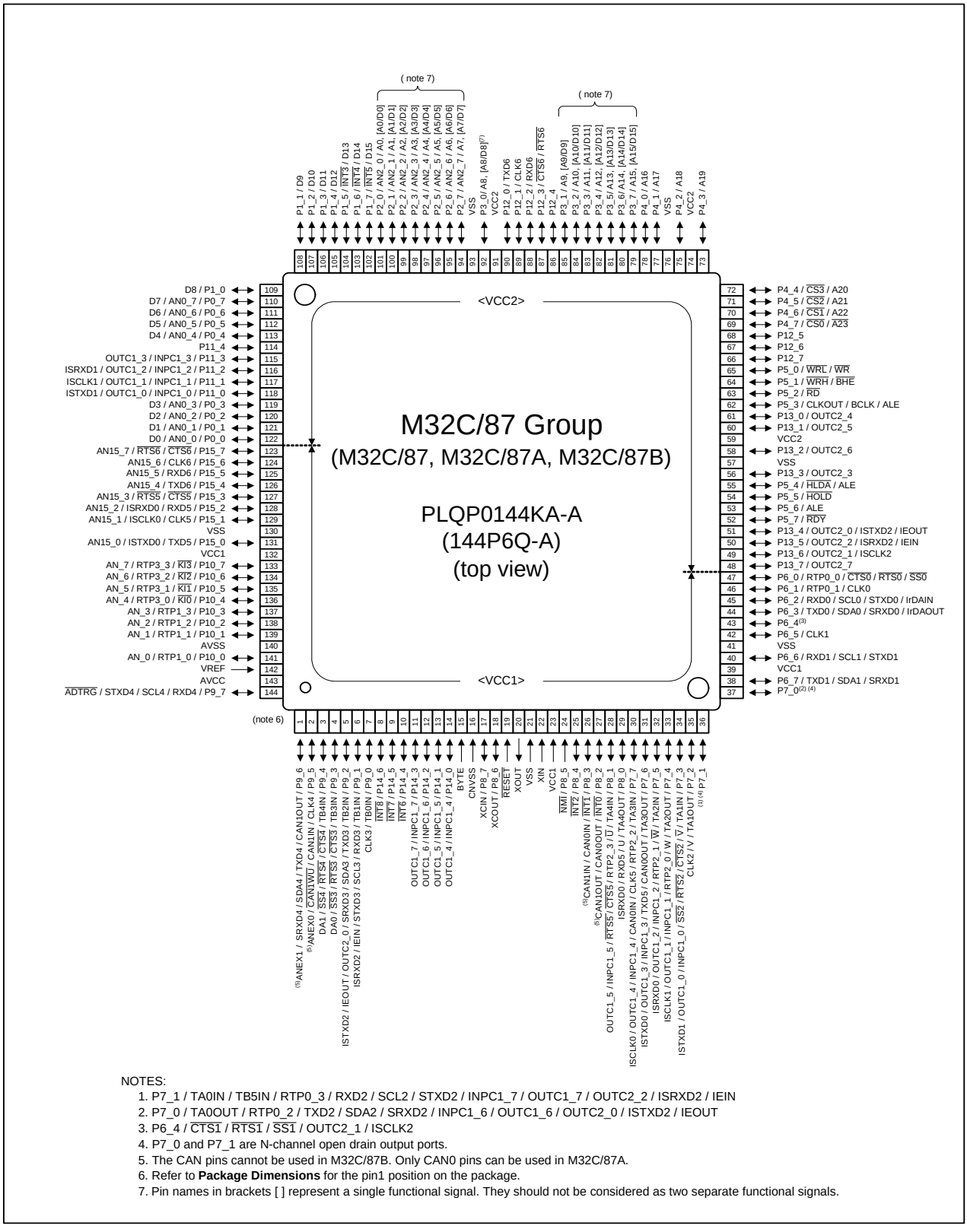
Tables 1.1 to 1.4 list the specifications of the M32C/87 Group (M32C/87, M32C/87A, M32C/87B).

Table 1.1 Specifications (144-Pin Package) (1/2)

Item	Function	Specification
CPU	Central processing unit	M32C/80 core (multiplier: 16 bits × 16 bits → 32 bits multiply-addition operation instructions: 16 × 16 + 48 → 48 bits) • Basic instructions: 108 • Minimum instruction execution time: 31.3 ns (f(CPU) = 32 MHz, VCC1 = 4.2 to 5.5 V) 41.7 ns (f(CPU) = 24 MHz, VCC1 = 3.0 to 5.5 V) • Operating modes: Single-chip mode, memory expansion mode, and microprocessor mode
Memory	ROM, RAM, data flash	See **Tables 1.5 to 1.7 Product List**.
Power Supply Voltage Detection		Vdet3 detection function, Vdet4 detection function, cold start/warm start determination function
External Bus Expansion	Bus/memory expansion function	• Address space: 16 Mbytes • External bus interface: 1 to 7 wait states can be inserted, 4 chip select outputs, 3 V and 5 V interfaces • Bus format: Switchable between separate bus and multiplexed bus formats, switchable data bus width (8-bit or 16-bit)
Clock	Clock generation circuits	• 4 circuits: Main clock, sub clock, on-chip oscillator, PLL frequency synthesizer • Oscillation stop detection: Main clock oscillation stop detection function • Frequency divider circuit: Dividing ratio selectable among 1, 2, 3, 4, 6, 8, 10, 12, 14, 16 • Low power consumption features: Wait mode, stop mode
Interrupts		• Interrupt vectors: 70 • External interrupt inputs: 14 ($\overline{\text{NMI}}$, $\overline{\text{INT}}$ × 9, key input × 4) • Interrupt priority levels: 7
Watchdog Timer		15-bit × 1 channel (with prescaler)
DMA	DMAC	• 4 channels, cycle steal method • Trigger sources: 43 • Transfer modes: 2 (single transfer and repeat transfer)
	DMACII	• Can be activated by all peripheral function interrupt sources • Transfer modes: 2 (single transfer and burst transfer) • Immediate transfer, calculation transfer, and chain transfer functions
Timer	Timer A	16-bit timer × 5 Timer mode, event counter mode, one-shot timer mode, pulse width modulation (PWM) mode, Event counter 2-phase pulse signal processing (2-phase encoder input) × 3
	Timer B	16-bit timer × 6 Timer mode, event counter mode, pulse period measurement mode, pulse width measurement mode
	Timer function for 3-phase motor control	3-phase inverter control × 1 (using timer A1, timer A2, timer A4, and timer B2) On-chip dead time timer

1.4 Pin Assignments

Figures 1.3 to 1.5 show pin assignments (top view).



NOTES:
1. P7_1 / TA0IN / TB5IN / RTP0_3 / RXD2 / SCL2 / STXD2 / INPC1_7 / OUTC1_7 / OUTC2_2 / ISRXD2 / IEIN
2. P7_0 / TA0OUT / RTP0_2 / TXD2 / SDA2 / SRXD2 / INPC1_6 / OUTC1_6 / OUTC2_0 / ISTXD2 / IEOUT
3. P6_4 / $\overline{\text{CTS1}}$ / $\overline{\text{RTS1}}$ / $\overline{\text{SS1}}$ / OUTC2_1 / ISCLK2
4. P7_0 and P7_1 are N-channel open drain output ports.
5. The CAN pins cannot be used in M32C/87B. Only CAN0 pins can be used in M32C/87A.
6. Refer to **Package Dimensions** for the pin1 position on the package.
7. Pin names in brackets [ ] represent a single functional signal. They should not be considered as two separate functional signals.

Figure 1.3 Pin Assignment for 144-Pin Package

Table 1.12 100-Pin Package List of Pin Names (1/3)

Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART/CAN Pin(1)	Intelligent I/O Pin	Analog Pin	Bus Control Pin
FP	GP								
1	99		P9_6			TXD4/SDA4/SRXD4/ CAN1OUT		ANEX1	
2	100		P9_5			CLK4/CAN1IN/ CAN1WU		ANEX0	
3	1		P9_4		TB4IN	CTS4/RTS4/SS4		DA1	
4	2		P9_3		TB3IN	CTS3/RTS3/SS3		DA0	
5	3		P9_2		TB2IN	TXD3/SDA3/SRXD3	OUTC2_0/IEOUT/ISTXD2		
6	4		P9_1		TB1IN	RXD3/SCL3/STXD3	IEIN/ISRXD2		
7	5		P9_0		TB0IN	CLK3			
8	6	BYTE							
9	7	CNVSS							
10	8	XCIN	P8_7						
11	9	XCOUT	P8_6						
12	10	RESET							
13	11	XOUT							
14	12	VSS							
15	13	XIN							
16	14	VCC1							
17	15		P8_5	NMI					
18	16		P8_4	INT2					
19	17		P8_3	INT1		CAN0IN/CAN1IN			
20	18		P8_2	INT0		CAN0OUT/CAN1OUT			
21	19		P8_1		TA4IN/U/RTP2_3	CTS5/RTS5	INPC1_5/OUTC1_5		
22	20		P8_0		TA4OUT/U	RXD5	ISRXD0		
23	21		P7_7		TA3IN/RTP2_2	CLK5/CAN0IN	INPC1_4/OUTC1_4/ ISCLK0		
24	22		P7_6		TA3OUT	TXD5/CAN0OUT	INPC1_3/OUTC1_3/ ISTXD0		
25	23		P7_5		TA2IN/W/RTP2_1		INPC1_2/OUTC1_2 ISRXD1		
26	24		P7_4		TA2OUT/W/ RTP2_0		INPC1_1/OUTC1_1/ ISCLK1		
27	25		P7_3		TA1IN/V	CTS2/RTS2/SS2	INPC1_0/OUTC1_0/ ISTXD1		
28	26		P7_2		TA1OUT/V	CLK2			
29	27		P7_1		TA0IN/TB5IN/ RTP0_3	RXD2/SCL2/STXD2	INPC1_7/OUTC1_7/ OUTC2_2/ISRXD2/IEIN		
30	28		P7_0		TA0OUT/RTP0_2	TXD2/SDA2/SRXD2	INPC1_6/OUTC1_6/ OUTC2_0/ISTXD2/IEOUT		
31	29		P6_7			TXD1/SDA1/SRXD1			
32	30		P6_6			RXD1/SCL1/STXD1			
33	31		P6_5			CLK1			
34	32		P6_4			CTS1/RTS1/SS1	OUTC2_1/ISCLK2		
35	33		P6_3			TXD0/SDA0/SRXD0/ IrDAOUT			
36	34		P6_2			RXD0/SCL0/STXD0/ IrDAIN			
37	35		P6_1		RTP0_1	CLK0			
38	36		P6_0		RTP0_0	CTS0/RTS0/SS0			
39	37		P5_7						RDY
40	38		P5_6						ALE

NOTE:
1. The CAN pins cannot be used in M32C/87B. Only CAN0 pins can be used in M32C/87A.

Table 1.16 Pin Functions (100-Pin and 144-Pin Packages) (2/4)

Type	Symbol	I/O Type	Supply Voltage	Description
Main clock input	XIN	I	VCC1	Input/output pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT. To apply an external clock, apply it to XIN and leave XOUT open.
Main clock output	XOUT	O	VCC1	
Sub clock input	XCIN	I	VCC1	Input/output pins for the sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT. To apply an external clock, apply it to XCIN and leave XCOUT open.
Sub clock output	XCOUT	O	VCC1	
BCLK output	BCLK	O	VCC2	Bus clock output pin.
Clock output	CLKOUT	O	VCC2	The CLKOUT pin outputs the clock having the same frequency as fC, f8, or f32.
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT2}}$	I	VCC1	$\overline{\text{INT}}$ interrupt input pins.
	$\overline{\text{INT3}}$ to $\overline{\text{INT5}}$	I	VCC2	
$\overline{\text{NMI}}$ interrupt input	$\overline{\text{NMI}}$	I	VCC1	$\overline{\text{NMI}}$ interrupt input pin. Connect the $\overline{\text{NMI}}$ pin to VCC1 via a resistor when the $\overline{\text{NMI}}$ interrupt is not used.
Timer A	TA0OUT to TA4OUT	I/O	VCC1	Timer A0 to A4 input/output pins. (TA0OUT is N-channel open drain output.)
	TA0IN to TA4IN	I	VCC1	Timer A0 to A4 input pins.
Timer B	TB0IN to TB5IN	I	VCC1	Timer B0 to B5 input pins.
Three-phase motor control timer output	U, $\overline{\text{U}}$, V, $\overline{\text{V}}$, W, $\overline{\text{W}}$	O	VCC1	Three-phase motor control timer output pins.
Serial interface	$\overline{\text{CTS0}}$ to $\overline{\text{CTS5}}$	I	VCC1	Input pins to control data transmission.
	$\overline{\text{RTS0}}$ to $\overline{\text{RTS5}}$	O	VCC1	Output pins to control data reception.
	CLK0 to CLK5	I/O	VCC1	Serial clock input/output pins.
	RXD0 to RXD5	I	VCC1	Serial data input pins.
	TXD0 to TXD5	O	VCC1	Serial data output pins. (TXD2 is N-channel open drain output.)
I^2C mode	SDA0 to SDA4	I/O	VCC1	Serial data input/output pins. (SDA2 is N-channel open drain output.)
	SCL0 to SCL4	I/O	VCC1	Serial clock input/output pins. (SCL2 is N-channel open drain output.)
Serial interface special function	STXD0 to STXD4	O	VCC1	Serial data output pins when slave mode is selected. (STXD2 is N-channel open drain output.)
	SRXD0 to SRXD4	I	VCC1	Serial data input pins when slave mode is selected.
	$\overline{\text{SS0}}$ to $\overline{\text{SS4}}$	I	VCC1	Control input pins used in the serial interface special mode.
IrDA	IrDAIN	I	VCC1	IrDA serial data input pin.
	IrDAOUT	O	VCC1	IrDA serial data output pin.
CAN(1)	CAN0IN, CAN1IN	I	VCC1	Received data input pins for the CAN communication function.
	CAN0OUT, CAN1OUT	O	VCC1	Transmit data output pins for the CAN communication function.
	$\overline{\text{CAN1WU}}$	I	VCC1	CAN wake-up interrupt input pin.

I: Input O: Output I/O: Input and output

NOTE:

1. The CAN pins cannot be used in M32C/87B. Only CAN0 pins can be used in M32C/87A.

Table 4.4 SFR Address Map (4/20)

Address	Register	Symbol	After Reset
0090h	UART0 Transmit/NACK Interrupt Control Register	S0TIC	XXXX X000b
0091h	UART1/UART4 Bus Conflict Detection Interrupt Control Register	BCN1IC/BCN4IC	XXXX X000b
0092h	UART1 Transmit/NACK Interrupt Control Register	S1TIC	XXXX X000b
0093h	Key Input Interrupt Control Register	KUPIC	XXXX X000b
0094h	Timer B0 Interrupt Control Register	TB0IC	XXXX X000b
0095h	II/O Interrupt Control Register 1 / CAN1 Interrupt Control Register 1	IIO1IC/CAN4IC	XXXX X000b
0096h	Timer B2 Interrupt Control Register	TB2IC	XXXX X000b
0097h	II/O Interrupt Control Register 3	IIO3IC	XXXX X000b
0098h	Timer B4 Interrupt Control Register	TB4IC	XXXX X000b
0099h	II/O Interrupt Control Register 5 /CAN1 Interrupt Control Register 2	IIO5IC/CAN5IC	XXXX X000b
009Ah	$\overline{\text{INT4}}$ Interrupt Control Register	INT4IC	XX00 X000b
009Bh	II/O Interrupt Control Register 7	IIO7IC	XXXX X000b
009Ch	$\overline{\text{INT2}}$ Interrupt Control Register	INT2IC	XX00 X000b
009Dh	II/O Interrupt Control Register 9 / CAN0 Interrupt Control Register 0	IIO9IC/CAN0IC	XXXX X000b
009Eh	$\overline{\text{INT0}}$ Interrupt Control Register	INT0IC	XX00 X000b
009Fh	Exit Priority Register	RLVL	XXXX 0000b
00A0h	Interrupt Request Register 0	IIO0IR	0000 000Xb
00A1h	Interrupt Request Register 1	IIO1IR	0000 000Xb
00A2h	Interrupt Request Register 2	IIO2IR	0000 000Xb
00A3h	Interrupt Request Register 3	IIO3IR	0000 000Xb
00A4h	Interrupt Request Register 4	IIO4IR	0000 000Xb
00A5h	Interrupt Request Register 5	IIO5IR	0000 000Xb
00A6h	Interrupt Request Register 6	IIO6IR	0000 000Xb
00A7h	Interrupt Request Register 7	IIO7IR	0000 000Xb
00A8h	Interrupt Request Register 8	IIO8IR	0000 000Xb
00A9h	Interrupt Request Register 9	IIO9IR	0000 000Xb
00AAh	Interrupt Request Register 10	IIO10IR	0000 000Xb
00ABh	Interrupt Request Register 11	IIO11IR	0000 000Xb
00ACh			
00ADh			
00AEh			
00AFh			
00B0h	Interrupt Enable Register 0	IIO0IE	00h
00B1h	Interrupt Enable Register 1	IIO1IE	00h
00B2h	Interrupt Enable Register 2	IIO2IE	00h
00B3h	Interrupt Enable Register 3	IIO3IE	00h
00B4h	Interrupt Enable Register 4	IIO4IE	00h
00B5h	Interrupt Enable Register 5	IIO5IE	00h
00B6h	Interrupt Enable Register 6	IIO6IE	00h
00B7h	Interrupt Enable Register 7	IIO7IE	00h
00B8h	Interrupt Enable Register 8	IIO8IE	00h
00B9h	Interrupt Enable Register 9	IIO9IE	00h
00BAh	Interrupt Enable Register 10	IIO10IE	00h
00BBh	Interrupt Enable Register 11	IIO11IE	00h
00BCh			
00BDh			
00BEh			
00BFh to 00DFh			

X: Undefined
Blank spaces are all reserved. No access is allowed.

Table 4.8 SFR Address Map (8/20)

Address	Register	Symbol	After Reset
01C0h	UART5 Transmit/Receive Mode Register	U5MR	00h
01C1h	UART5 Baud Rate Register	U5BRG	XXh
01C2h	UART5 Transmit Buffer Register	U5TB	XXXXh
01C3h			
01C4h	UART5 Transmit/Receive Control Register 0	U5C0	0000 1000b
01C5h	UART5 Transmit/Receive Control Register 1	U5C1	XXXX 0010b
01C6h	UART5 Receive Buffer Register	U5RB	XXXXh
01C7h			
01C8h	UART6 Transmit/Receive Mode Register	U6MR	00h
01C9h	UART6 Baud Rate Register	U6BRG	XXh
01CAh	UART6 Transmit Buffer Register	U6TB	XXXXh
01CBh			
01CCh	UART6 Transmit/Receive Control Register 0	U6C0	0000 1000b
01CDh	UART6 Transmit/Receive Control Register 1	U6C1	XXXX 0010b
01CEh	UART6 Receive Buffer Register	U6RB	XXXXh
01CFh			
01D0h	UART5, UART6 Transmit/Receive Control Register	U56CON	X000 0000b
01D1h	UART5, UART6 Input Pin Function Select Register	U56IS	X000 X000b
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h	RTP Output Buffer Register 0	RTP0R	XXh
01D9h	RTP Output Buffer Register 1	RTP1R	XXh
01DAh	RTP Output Buffer Register 2	RTP2R	XXh
01DBh	RTP Output Buffer Register 3	RTP3R	XXh
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	CAN0 Message Slot Buffer 0 Standard ID0(1)(2)	C0SLOT0_0	XXh
01E1h	CAN0 Message Slot Buffer 0 Standard ID1(1)(2)	C0SLOT0_1	XXh
01E2h	CAN0 Message Slot Buffer 0 Extended ID0(1)(2)	C0SLOT0_2	XXh
01E3h	CAN0 Message Slot Buffer 0 Extended ID1(1)(2)	C0SLOT0_3	XXh
01E4h	CAN0 Message Slot Buffer 0 Extended ID2(1)(2)	C0SLOT0_4	XXh
01E5h	CAN0 Message Slot Buffer 0 Data Length Code(1)(2)	C0SLOT0_5	XXh
01E6h	CAN0 Message Slot Buffer 0 Data 0(1)(2)	C0SLOT0_6	XXh
01E7h	CAN0 Message Slot Buffer 0 Data 1(1)(2)	C0SLOT0_7	XXh
01E8h	CAN0 Message Slot Buffer 0 Data 2(1)(2)	C0SLOT0_8	XXh
01E9h	CAN0 Message Slot Buffer 0 Data 3(1)(2)	C0SLOT0_9	XXh
01EAh	CAN0 Message Slot Buffer 0 Data 4(1)(2)	C0SLOT0_10	XXh
01EBh	CAN0 Message Slot Buffer 0 Data 5(1)(2)	C0SLOT0_11	XXh
01ECh	CAN0 Message Slot Buffer 0 Data 6(1)(2)	C0SLOT0_12	XXh
01EDh	CAN0 Message Slot Buffer 0 Data 7(1)(2)	C0SLOT0_13	XXh
01EEh	CAN0 Message Slot Buffer 0 Time Stamp High-Order(1)(2)	C0SLOT0_14	XXh
01EFh	CAN0 Message Slot Buffer 0 Time Stamp Low-Order(1)(2)	C0SLOT0_15	XXh

X: Undefined
Blank spaces are all reserved. No access is allowed.

NOTES:

1. The CAN-associated registers (allocated in addresses 01E0h to 02BFh) cannot be used in M32C/87B. In M32C/87A, only CAN0-associated registers can be used.
2. Set the PM13 bit in the PM1 register to 1 (2 wait states for SFR area) before accessing the CAN-associated registers.

Table 4.11 SFR Address Map (11/20)

Address	Register[2][3]	Symbol	After Reset
0250h	CAN1 Slot Buffer Select Register	C1SBS	00h[1]
0251h	CAN1 Control Register 1	C1CTLR1	X000 00XXb[1]
0252h	CAN1 Sleep Control Register	C1SLPR	XXXX XXX0b[1]
0253h			
0254h	CAN1 Acceptance Filter Support Register	C1AFS	0000 0000b[1]
0255h			0000 0001b[1]
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h	CAN1 Message Slot Buffer 0 Standard ID0	C1SLOT0_0	XXh
0261h	CAN1 Message Slot Buffer 0 Standard ID1	C1SLOT0_1	XXh
0262h	CAN1 Message Slot Buffer 0 Extended ID0	C1SLOT0_2	XXh
0263h	CAN1 Message Slot Buffer 0 Extended ID1	C1SLOT0_3	XXh
0264h	CAN1 Message Slot Buffer 0 Extended ID2	C1SLOT0_4	XXh
0265h	CAN1 Message Slot Buffer 0 Data Length Code	C1SLOT0_5	XXh
0266h	CAN1 Message Slot Buffer 0 Data 0	C1SLOT0_6	XXh
0267h	CAN1 Message Slot Buffer 0 Data 1	C1SLOT0_7	XXh
0268h	CAN1 Message Slot Buffer 0 Data 2	C1SLOT0_8	XXh
0269h	CAN1 Message Slot Buffer 0 Data 3	C1SLOT0_9	XXh
026Ah	CAN1 Message Slot Buffer 0 Data 4	C1SLOT0_10	XXh
026Bh	CAN1 Message Slot Buffer 0 Data 5	C1SLOT0_11	XXh
026Ch	CAN1 Message Slot Buffer 0 Data 6	C1SLOT0_12	XXh
026Dh	CAN1 Message Slot Buffer 0 Data 7	C1SLOT0_13	XXh
026Eh	CAN1 Message Slot Buffer 0 Time Stamp High-Order	C1SLOT0_14	XXh
026Fh	CAN1 Message Slot Buffer 0 Time Stamp Low-Order	C1SLOT0_15	XXh
0270h	CAN1 Message Slot Buffer 1 Standard ID0	C1SLOT1_0	XXh
0271h	CAN1 Message Slot Buffer 1 Standard ID1	C1SLOT1_1	XXh
0272h	CAN1 Message Slot Buffer 1 Extended ID0	C1SLOT1_2	XXh
0273h	CAN1 Message Slot Buffer 1 Extended ID1	C1SLOT1_3	XXh
0274h	CAN1 Message Slot Buffer 1 Extended ID2	C1SLOT1_4	XXh
0275h	CAN1 Message Slot Buffer 1 Data Length Code	C1SLOT1_5	XXh
0276h	CAN1 Message Slot Buffer 1 Data 0	C1SLOT1_6	XXh
0277h	CAN1 Message Slot Buffer 1 Data 1	C1SLOT1_7	XXh
0278h	CAN1 Message Slot Buffer 1 Data 2	C1SLOT1_8	XXh
0279h	CAN1 Message Slot Buffer 1 Data 3	C1SLOT1_9	XXh
027Ah	CAN1 Message Slot Buffer 1 Data 4	C1SLOT1_10	XXh
027Bh	CAN1 Message Slot Buffer 1 Data 5	C1SLOT1_11	XXh
027Ch	CAN1 Message Slot Buffer 1 Data 6	C1SLOT1_12	XXh
027Dh	CAN1 Message Slot Buffer 1 Data 7	C1SLOT1_13	XXh
027Eh	CAN1 Message Slot Buffer 1 Time Stamp High-Order	C1SLOT1_14	XXh
027Fh	CAN1 Message Slot Buffer 1 Time Stamp Low-Order	C1SLOT1_15	XXh

X: Undefined
Blank spaces are all reserved. No access is allowed.
NOTES:
1. Values are obtained by setting the SLEEP bit in the C1SLPR register to “1” (sleep mode exited) after reset and supplying a clock to the CAN module.
2. The CAN-associated registers (allocated in addresses 01E0h to 02BFh) cannot be used in M32C/87B. In M32C/87A, only CAN0-associated registers can be used.
3. Set the PM13 bit in the PM1 register to 1 (2 wait states for SFR area) before accessing the CAN-associated registers.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Value	Unit
VCC1, VCC2	Supply voltage		VCC1 = AVCC	-0.3 to 6.0	V
VCC2	Supply voltage		–	-0.3 to VCC1 + 0.1	V
AVCC	Analog supply voltage		VCC1 = AVCC	-0.3 to 6.0	V
VI	Input voltage	$\overline{\text{RESET}}$, CNVSS, BYTE, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(1), VREF, XIN		-0.3 to VCC1 + 0.3	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(1)		-0.3 to VCC2 + 0.3	
		P7_0, P7_1		-0.3 to 6.0	
VO	Output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P14_0 to 14_6, P15_0 to P15_7(1), XOUT		-0.3 to VCC1 + 0.3	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(1)		-0.3 to VCC2 + 0.3	
		P7_0, P7_1		-0.3 to 6.0	
Pd	Power consumption		-40°C≤Topr≤85°C	500	mW
Topr	Operating ambient temperature	during CPU operation		-20 to 85/ -40 to 85(2)	°C
		during programming or erasing Flash memory		0 to 60	°C
Tstg	Storage temperature			-65 to 150	°C

NOTES:
1. P11 to P15 are provided in the 144-pin package only.
2. Contact a Renesas sales office if temperature range of -40 to 85°C is required.

Table 5.2 Recommended Operating Conditions (1/3)
(VCC1 = VCC2 = 3.0 to 5.5 V, Topr = -20 to 85°C unless otherwise specified)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
VCC1, VCC2	Supply voltage (VCC1 ≥ VCC2)		3.0	5.0	5.5	V
AVCC	Analog supply voltage			VCC1		V
VSS	Supply voltage			0		V
AVSS	Analog supply voltage			0		V
VIH	Input high “H” voltage	P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(2)	0.8VCC2		VCC2	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7(1), P9_0 to P9_7, P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(2), XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0.8VCC1		VCC1	
		P7_0, P7_1	0.8VCC1		6.0	
		P0_0 to P0_7, P1_0 to P1_7 (in single-chip mode)	0.8VCC2		VCC2	
		P0_0 to P0_7, P1_0 to P1_7 (in memory expansion mode and microprocessor mode)	0.5VCC2		VCC2	
VIL	Input low “L” voltage	P2_0 to P2_7,P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(2)	0		0.2VCC2	V
		P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7(1), P9_0 to P9_7, P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(2), XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0		0.2VCC1	
		P0_0 to P0_7, P1_0 to P1_7 (in single-chip mode)	0		0.2VCC2	
		P0_0 to P0_7, P1_0 to P1_7 (in memory expansion mode and microprocessor mode)	0		0.16VCC2	

NOTES:
1. VIH and VIL reference for P8_7 apply when P8_7 is used as a programmable input port. It does not apply when P8_7 is used as XCIN.
2. P11 to P15 are provided in the 144-pin package only.

VCC1 = VCC2 = 5V

Timing Requirements
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.13 External Clock Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc	External clock input cycle time	31.25		ns
tw(H)	External clock input high (“H”) pulse width	13.75		ns
tw(L)	External clock input low (“L”) pulse width	13.75		ns
tr	External clock rise time		5	ns
tf	External clock fall time		5	ns

Table 5.14 Timer A Input (Count Source Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	100		ns
tw(TAH)	TAiIN input high (“H”) pulse width	40		ns
tw(TAL)	TAiIN input low (“L”) pulse width	40		ns

i = 0 to 4

Table 5.15 Timer A Input (Gate Signal Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	400		ns
tw(TAH)	TAiIN input high (“H”) pulse width	200		ns
tw(TAL)	TAiIN input low (“L”) pulse width	200		ns

i = 0 to 4

Table 5.16 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	200		ns
tw(TAH)	TAiIN input high (“H”) pulse width	100		ns
tw(TAL)	TAiIN input low (“L”) pulse width	100		ns

i = 0 to 4

Table 5.17 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tw(TAH)	TAiIN input high (“H”) pulse width	100		ns
tw(TAL)	TAiIN input low (“L”) pulse width	100		ns

i = 0 to 4

VCC1 = VCC2 = 5V

Timing Requirements
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.28 Memory Expansion mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tac1(RD-DB)	Data input access time (RD standard)		(note 1)	ns
tac1(AD-DB)	Data input access time (AD standard, CS standard)		(note 1)	ns
tac2(RD-DB)	Data input access time (RD standard, when accessing a space with the multiplexed bus)		(note 1)	ns
tac2(AD-DB)	Data input access time (AD standard, when accessing a space with the multiplexed bus)		(note 1)	ns
tsu(DB-BCLK)	Data input setup time	26		ns
tsu(RDY-BCLK)	$\overline{\text{RDY}}$ input setup time	26		ns
tsu(HOLD-BCLK)	$\overline{\text{HOLD}}$ input setup time	30		ns
th(RD-DB)	Data input hold time	0		ns
th(BCLK-RDY)	$\overline{\text{RDY}}$ input hold time	0		ns
th(BCLK-HOLD)	$\overline{\text{HOLD}}$ input hold time	0		ns
td(BCLK-HLDA)	$\overline{\text{HLDA}}$ output delay time		25	ns

NOTE:
1. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equations. Insert wait states or lower the operation frequency, f(BCLK), if the calculated value is negative.

$$\text{tac1(RD-DB)} = \frac{10^9 \times m}{f(BCLK) \times 2} - 35\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $m = (b \times 2) + 1$)

$$\text{tac1(AD-DB)} = \frac{10^9 \times n}{f(BCLK)} - 35\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $n = a + b$)

$$\text{tac2(RD-DB)} = \frac{10^9 \times m}{f(BCLK) \times 2} - 35\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $m = (b \times 2) - 1$)

$$\text{tac2(AD-DB)} = \frac{10^9 \times p}{f(BCLK) \times 2} - 35\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $p = \{(a + b - 1) \times 2\} + 1$)

VCC1 = VCC2 = 5V

Switching Characteristics
(VCC1 = VCC2 = 4.2 to 5.5 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.30 Memory Expansion Mode and Microprocessor Mode (when accessing external memory space with multiplexed bus)

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min.	Max.	
td(BCLK-AD)	Address output delay time	See Figure 5.2		18	ns
th(BCLK-AD)	Address output hold time (BCLK standard)		-3		ns
th(RD-AD)	Address output hold time (RD standard)(5)		(note 1)		ns
th(WR-AD)	Address output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-CS)	Chip-select signal output delay time			18	ns
th(BCLK-CS)	Chip-select signal output hold time (BCLK standard)		-3		ns
th(RD-CS)	Chip-select signal output hold time (RD standard)(5)		(note 1)		ns
th(WR-CS)	Chip-select signal output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-RD)	RD signal output delay time			18	ns
th(BCLK-RD)	RD signal output hold time		-5		ns
td(BCLK-WR)	WR signal output delay time			18	ns
th(BCLK-WR)	WR signal output hold time		-5		ns
td(DB-WR)	Data output delay time (WR standard)		(note 2)		ns
th(WR-DB)	Data output hold time (WR standard)(5)		(note 1)		ns
td(BCLK-ALE)	ALE signal output delay time (BCLK standard)			18	ns
th(BCLK-ALE)	ALE signal output hold time (BCLK standard)		-2		ns
td(AD-ALE)	ALE signal output delay time (address standard)		(note 3)		ns
th(ALE-AD)	ALE signal output hold time (address standard)		(note 4)		ns
tdz(RD-AD)	Address output float start time			8	ns

NOTES:

1. Values, which depend on BCLK frequency, can be obtained from the following equations.

$$th(RD\text{-}AD) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}AD) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(RD\text{-}CS) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}CS) = \frac{10^9}{f(BCLK) \times 2} - 10\ [ns]$$

$$th(WR\text{-}DB) = \frac{10^9}{f(BCLK) \times 2} - 15\ [ns]$$

2. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

$$td(DB\text{-}WR) = \frac{10^9 \times m}{f(BCLK) \times 2} - 25\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $m = (b \times 2) - 1$)

3. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

$$td(AD\text{-}ALE) = \frac{10^9 \times n}{f(BCLK) \times 2} - 20\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $n = a$)

4. Values, which depend on BCLK frequency and external bus cycles, can be obtained from the following equation.

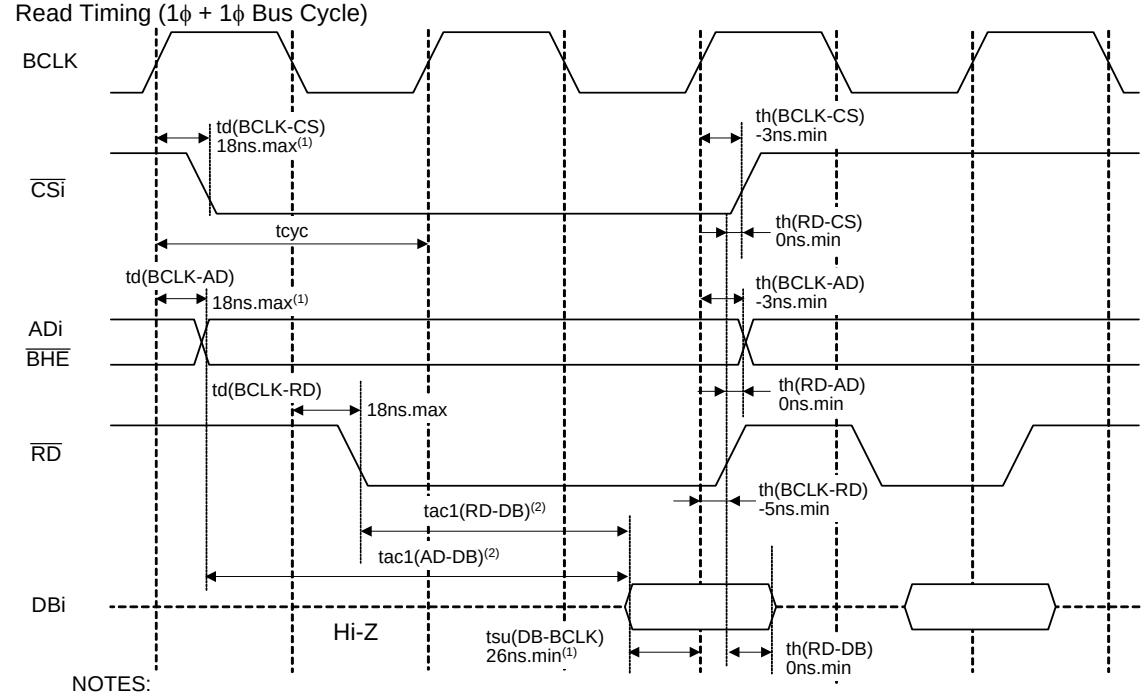
$$th(ALE\text{-}AD) = \frac{10^9 \times n}{f(BCLK) \times 2} - 20\ [ns]$$ (if external bus cycle is $a\phi + b\phi$, $n = a$)

5. tc [ns] is added when recovery cycle is inserted.

Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space)

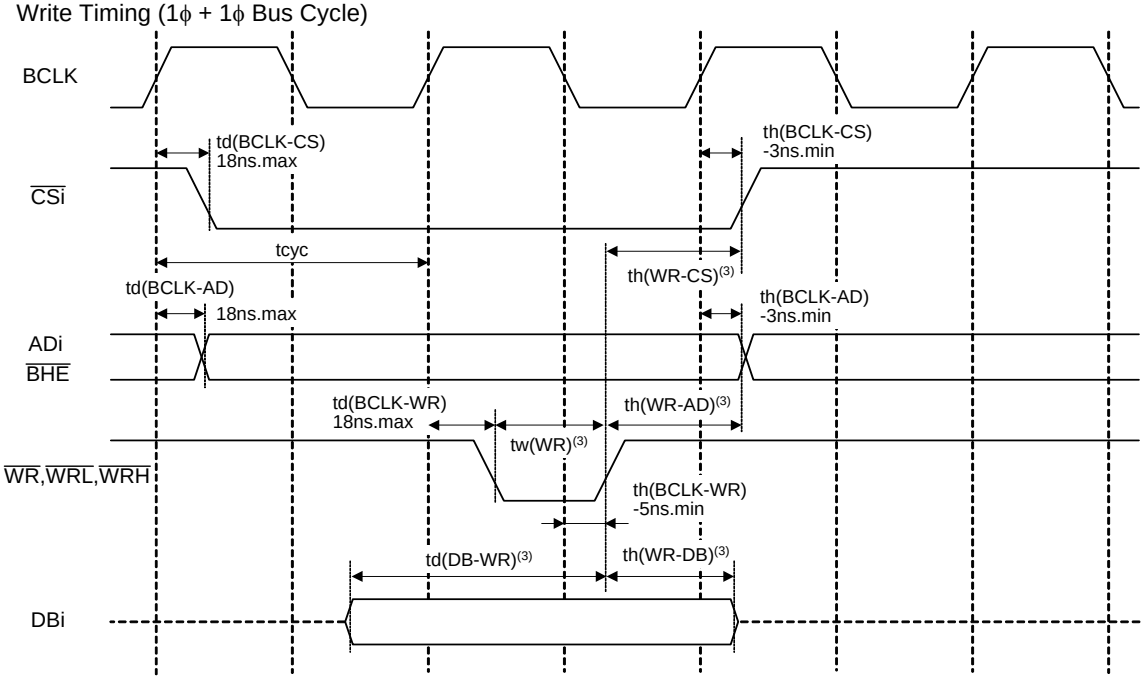
VCC1=VCC2=5V

Read Timing (1φ + 1φ Bus Cycle)



NOTES:
1. Values guaranteed only when the MCU is used stand-alone.
   A maximum of 35 ns is guaranteed for td(BCLK-AD) + tsu(DB-BCLK).
2. Varies with operation frequency:
   tac1(RD-DB) = (tcyc / 2 x m - 35) ns.max (if external bus cycle aφ + bφ, m = (b x 2) + 1)
   tac1(AD-DB) = (tcyc x n - 35) ns.max (if external bus cycle aφ + bφ, n = a + b)

Write Timing (1φ + 1φ Bus Cycle)



NOTES:
3. Varies with operation frequency:
   td(DB-WR) = (tcyc x m - 20) ns.min
   (if external bus cycle aφ + bφ, m = b)
   th(WR-DB) = (tcyc / 2 - 15) ns.min
   th(WR-AD) = (tcyc / 2 - 10) ns.min
   th(WR-CS) = (tcyc / 2 - 10) ns.min
   tw(WR) = (tcyc / 2 x n - 15) ns.min
   (if external bus cycle aφ + bφ, n = (b x 2) - 1)

Measurement Conditions:
- VCC1 = VCC2 = 4.2 to 5.5 V
- Input high and low voltage: VIH = 2.5 V, VIL = 0.8 V
- Output high and low voltage: VOH = 2.0 V, VOL = 0.8 V

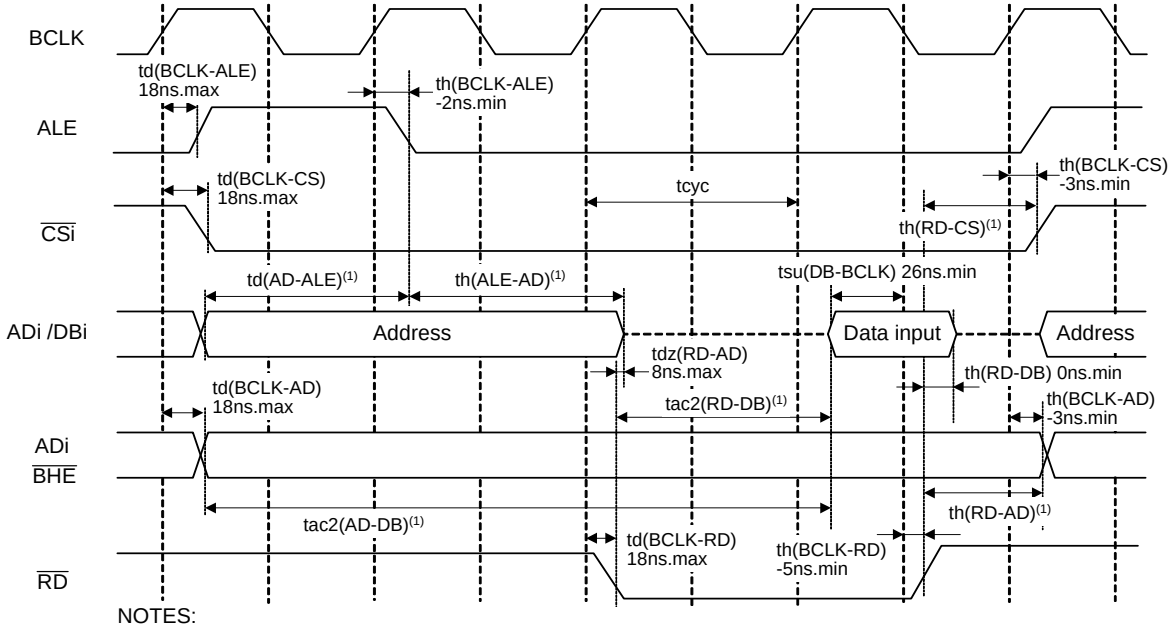
$$tcyc = \frac{10^9}{f(BCLK)}$$

Figure 5.5 VCC1 = VCC2 = 5 V Timing Diagram (3/4)

Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space with the multiplexed bus)

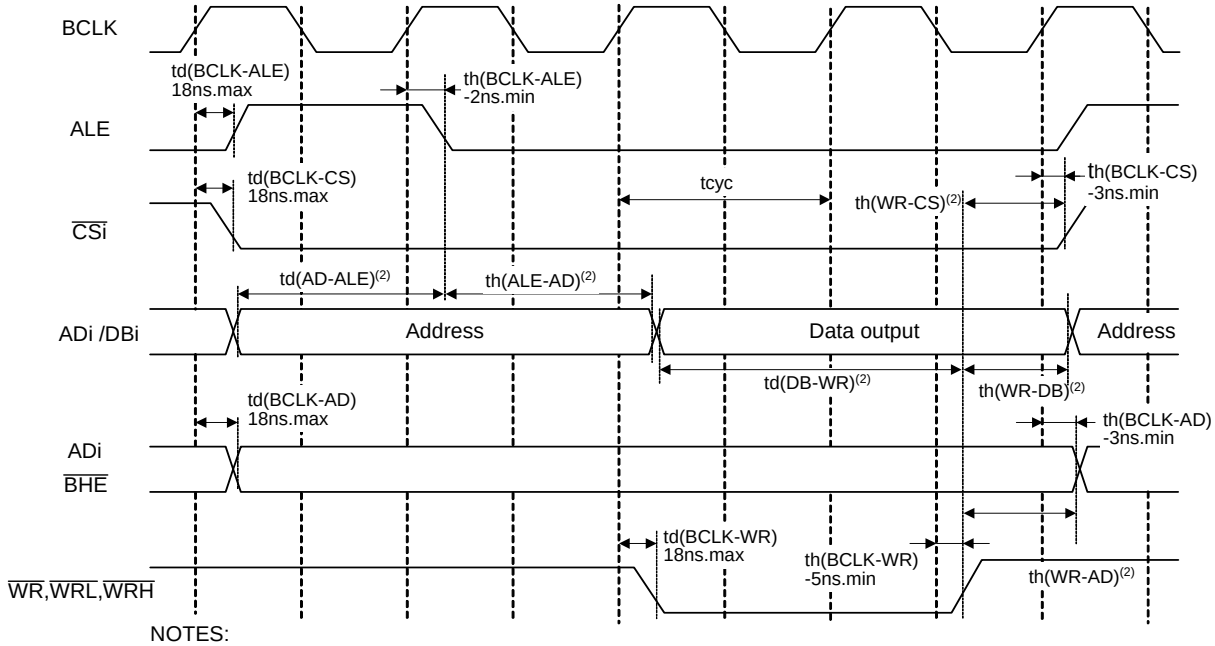
VCC1=VCC2=5V

Read Timing (2φ + 2φ Bus Cycle)



NOTES:
1. Varies with operation frequency:
td(AD-ALE) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(ALE-AD) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(RD-AD) = (tcyc / 2 - 10) ns.min, th(RD-CS) = (tcyc / 2 - 10) ns.min
tac2(RD-DB) = (tcyc / 2 x m - 35) ns.max (if external bus cycle aφ + bφ, m = (b x 2) - 1)
tac2(AD-DB) = (tcyc / 2 x p - 35) ns.max (if external bus cycle aφ + bφ, p = {(a + b - 1) x 2} + 1)

Write Timing (2φ + 2φ Bus Cycle)



NOTES:
1. Varies with operation frequency:
td(AD-ALE) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(ALE-AD) = (tcyc / 2 x n - 20) ns.min (if external bus cycle aφ + bφ, n = a)
th(WR-AD) = (tcyc / 2 - 10) ns.min, th(WR-CS) = (tcyc / 2 - 10) ns.min
th(WR-DB) = (tcyc / 2 - 15) ns.min
td(DB-WR) = (tcyc / 2 x m - 25) ns.min (if external bus cycle aφ + bφ, m = (b x 2) - 1)

$$tcyc = \frac{10^9}{f(BCLK)}$$

Measurement Conditions:
- VCC1 = VCC2 = 4.2 to 5.5 V
- Input high and low voltage VIH = 2.5 V, VIL = 0.8 V
- Output high and low voltage VOH = 2.0 V, VOL = 0.8 V

Figure 5.6 VCC1 = VCC2 = 5 V Timing Diagram (4/4)

VCC1 = VCC2 = 3.3 V

Table 5.31 Electrical Characteristics (1/3)

(VCC1 = VCC2 = 3.0 to 3.6 V, VSS = 0 V, Topr = -20 to 85°C, f(CPU) = 24 MHz unless otherwise specified)

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
VOH	Output high “H” voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7(1)	IOH = -1 mA	VCC2 - 0.6		VCC2	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P14_0 to P14_6, P15_0 to P15_7(1)		VCC1 - 0.6		VCC1	
		XOUT	IOH = -0.1 mA	2.7		VCC1	V
		XCOUT Drive capability = high	No load applied		2.5		V
		XCOUT Drive capability = low	No load applied		1.6		V
VOL	Output low “L” voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7,P10_0 to P10_7, P11_0 to P11_4, P12_0 to P12_7, P13_0 to P13_7, P14_0 to P14_6, P15_0 to P15_7(1)	IOL = 1 mA			0.5	V
		XOUT	IOL = 0.1 mA			0.5	V
		XCOUT Drive capability = high	No load applied		0		V
		XCOUT Drive capability = low	No load applied		0		V
VT+ - VT-	Hysteresis	$\overline{\text{HOLD}}$, $\overline{\text{RDY}}$, TA0IN to TA4IN, $\overline{\text{TB0IN}}$ to $\overline{\text{TB5IN}}$, $\overline{\text{INT0}}$ to $\overline{\text{INT8}}$, $\overline{\text{ADTRG}}$, $\overline{\text{CTS0}}$ to $\overline{\text{CTS6}}$, CLK0 to CLK6, TA0OUT to TA4OUT, $\overline{\text{NMI}}$, $\overline{\text{KI0}}$ to $\overline{\text{KI3}}$, RXD0 to RXD6, SCL0 to SCL4, SDA0 to SDA4, INPC1_0 to INPC1_7, ISCLK0 to ISCLK2, ISRXD0 to ISRXD2, IEIN, CAN0IN, CAN1IN, $\overline{\text{CAN1WU}}$		0.2		1.0	V
		$\overline{\text{RESET}}$		0.2		1.8	V

NOTE:

1. P11 to P15 are provided in the 144-pin package only.

VCC1 = VCC2 = 3.3 V

Timing Requirements
(VCC1 = VCC2 = 3.0 to 3.6 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.36 External Clock Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc	External clock input cycle time	41		ns
tw(H)	External clock input high (“H”) pulse width	18		ns
tw(L)	External clock input low (“L”) pulse width	18		ns
tr	External clock rise time		5	ns
tf	External clock fall time		5	ns

Table 5.37 Timer A Input (Count Source Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	100		ns
tw(TAH)	TAiIN input high (“H”) pulse width	40		ns
tw(TAL)	TAiIN input low (“L”) pulse width	40		ns

i = 0 to 4

Table 5.38 Timer A Input (Gate Signal Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	400		ns
tw(TAH)	TAiIN input high (“H”) pulse width	200		ns
tw(TAL)	TAiIN input low (“L”) pulse width	200		ns

i = 0 to 4

Table 5.39 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	200		ns
tw(TAH)	TAiIN input high (“H”) pulse width	100		ns
tw(TAL)	TAiIN input low (“L”) pulse width	100		ns

i = 0 to 4

Table 5.40 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tw(TAH)	TAiIN input high (“H”) pulse width	100		ns
tw(TAL)	TAiIN input low (“L”) pulse width	100		ns

i = 0 to 4

VCC1 = VCC2 = 3.3 V

Timing Requirements
(VCC1 = VCC2 = 3.0 to 3.6 V, VSS = 0 V, Topr = -20 to 85°C unless otherwise specified)

Table 5.46 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(AD)	$\overline{\text{ADTRG}}$ input cycle time (required for trigger)	1000		ns
tw(ADL)	$\overline{\text{ADTRG}}$ input low (“L”) pulse width	125		ns

Table 5.47 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(CK)	CLKi input cycle time	200		ns
tw(CKH)	CLKi input high (“H”) pulse width	100		ns
tw(CKL)	CLKi input low (“L”) pulse width	100		ns
td(C-Q)	TXDi output delay time		80	ns
th(C-Q)	TXDi output hold time	0		ns
tsu(D-C)	RXDi input setup time	70		ns
th(C-D)	RXDi input hold time	90		ns

i = 0 to 6

Table 5.48 Intelligent I/O Communication Function (Groups 0 and 1)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(CK)	ISCLKi input cycle time	600		ns
tw(CKH)	ISCLKi input high (“H”) pulse width	300		ns
tw(CKL)	ISCLKi input low (“L”) pulse width	300		ns
td(C-Q)	ISTXDi output delay time		100	ns
th(C-Q)	ISTXDi output hold time	0		ns
tsu(D-C)	ISRXDi input setup time	100		ns
th(C-D)	ISRXDi input hold time	100		ns

i = 0, 1

Table 5.49 Intelligent I/O Communication Function (Group 2)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(CK)	ISCLK2 input cycle time	600		ns
tw(CKH)	ISCLK2 input high (“H”) pulse width	300		ns
tw(CKL)	ISCLK2 input low (“L”) pulse width	300		ns
td(C-Q)	ISTXD2 output delay time		180	ns
th(C-Q)	ISTXD2 output hold time	0		ns
tsu(D-C)	ISRXD2 input setup time	150		ns
th(C-D)	ISRXD2 input hold time	100		ns

REVISION HISTORY	M32C/87 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.50	Dec.16, 04	–	New Document
1.00	Jul.14, 05	–	**M32C/87A and M32C/87B** added
		–	Package code changed: 144P6Q-A to PLQP0144KA-A, 100P6Q-A to PLQP0100KB-A, 100P6S-A to PRQP0100JB-A
		–	"Low Voltage Detection Reset" changed to "Brown-out Detection Reset"
			Overview
		2	• **Table 1.2 M32C/87 Group Performance (144-Pin Package)** M32C/87A and M32C/87B performance added to the CAN module performance; Power Consumption performance released
		3	• **Table 1.2 M32C/87 Group Performance (100-Pin Package)** M32C/87A and M32C/87B performance added to the CAN module performance; Power Consumption performance released
		4	• **Figure 1.1 M32C/87 Group Block Diagram** Note 4 deleted; note 5 added
		7	• **Figure 1.3 Pin Assignment for 144-Pin Package** Note 15 added
		8	• **Table 1.4 Pin Characteristics for 144-Pin Package** Note 1 added
		11	• **Figure 1.4 Pin Assignment for 100-Pin Package** Note 19 added
		12	• **Figure 1.5 Pin Assignment for 100-Pin Package** Note 15 added
		13	• **Table 1.5 Pin Characteristics for 100-Pin Package** Note 1 added
		17	• **Table 1.6 Pin Description** Note 2 added
			Memory
		22	• **Figure 3.1 Memory Map** Note 3 changed
			Special Function Register (SFR)
		26	• The RLVL register Value after reset modified
		26	• The IIO0IR to IIO11IR registers Value after reset modified
		27 to 30	• Name of the registers assosiated to Intelligent I/O changed
		27	• The G0RB register Value after reset modified
		27	• The G1BCR0 and G1BCR1 registers Value after reset modified
		29	• The G0CR register Value after reset modified
		32 to 37	• Note added to the CAN-associated registers
		40	• The TCSPR register Value after reset modified; note 1 added
		41	• The AD00 register Value after reset modified
		42	• The PSC register Value after reset modified
		42	• The PS2 register Value after reset modified
		43	• The PCR register Value after reset modified
		44	• The PSD1 register Value after reset modified
		45	• The PCR register Value after reset modified
			Electrical Characteristics
		48	• **Table 5.2 Electrical Characteristics** Parameter f(BCLK) and its values added; min. and max. values for f(RING) added
		49	• **Table 5.3 Electrical Characteristics** V_{OH} values modified**;** R_{PULLUP} value modified
		50	• **Table 5.3 Electrical Characteristics (Continued)** Measurement Condition and standard values for ICC added and some released
		52	• **Table 5.6 Flash Memory Version Electrical Characteristics** Word Program Time and Lock bit Program Time values modified; parameter All-Unlocked-Block-Erase Time deleted; note 1 deleted
		54	• **Table 5.10 Memory Expansion Mode and Microprocessor Mode** *tac1(RD-DB)* expression on note 1 modified; *tac2(RD-DB)* expression on note 1 added